



Item

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Yeshwanth Narendar et al.

Title: METHOD FOR TREATING SEMICONDUCTOR PROCESSING COMPONENTS AND COMPONENTS FORMED THEREBY

Application No.: 10/824,329

Filed: April 14, 2004

Examiner: Julio J. Maldonado

Group Art Unit: 2823

Atty. Docket No.: 1035-E4371

Customer No.: 34456

MS AMENDMENT
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to the Examiner's attention in the above-identified application. Citation of such information shall not be construed as:

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indicates the degree of relevance found by the foreign office.

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If the above-identified application is an original application filed on or after May 29, 2000:

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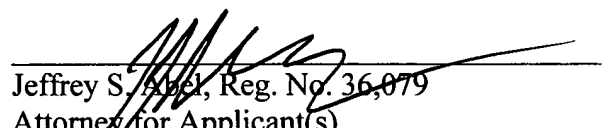
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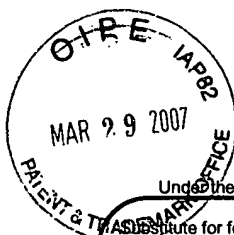
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Date

3/26/07

Respectfully submitted,


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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)				Complete if Known	
				Application Number	10/824,329
				Filing Date	April 14, 2004
				First Named Inventor	Yeshwanth Narendar
				Art Unit	2823
				Examiner Name	Julio J. Maldonado
Sheet	1	of	1	Attorney Docket Number	1035-E4371

NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
	A1	H. RAUH, "Atlas for Characterization of Defects in Silicon," Wacker Siltronic AG, Burghausen, Germany, pp. 1-64, 2004	
	B1	R. F. BUCKLEY et al., "Design and Analysis of a Semiconductor Wafer Processing System for 30 mm Wafers," MS Thesis - Worcester Polytechnic Institute, 12/29/99, pp 1-62	
	C1	B. LEROY et al., "Warping of Silicon Wafers," Journal Electrochemical Society, Vol. 127, No. 4, April 1980, pp. 961-970	
	D1	M. SCHREMS et al., "Simulation of Temperature Distributions During Fast Thermal Processing," Journal Electrochemical Society, Semiconductor Silicon, 1994, pp. 1050-1059	
	E1	NILSON et al., "Scaling wafer stresses and thermal processes to large wafers," Thin Solid Films 315, 1998, pp. 286-293	
	F1	VAN ZANT, "Microchip Fabrication: A Practical Guide to Semiconductor Processing," McGraw Hill, Fourth Edition, 1990, chapters 3-7	
	G1	SHIGLEY et al., "Mechanical Engineering Design," McGraw Hill, copyright 1989, p. 62, p. 159	
	H1	Machinery Handbook, 24th Edition, Industrial Press, Copyright 1992, pp. 1598-1603	
	I1		
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Examiner Signature		Date Considered	
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